PF01411A

MOS FET Power Amplifier Module for E-GSM Handy Phone

HITACHI

ADE-208-433C (Z) 4th Edition February 1997

Application

- For E-GSM class4 880 to 915 MHz
- For 4.8V nominal battery use

Features

• High gain 3stage amplifier: 0 dBm input

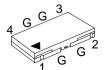
• Lead less thin & Small package: 2 mm Max, 0.2cc

• High efficiency: 45% Typ at 3.8 W

• Wide gain control range: 90 dB Typ

Pin Arrangement

• RF-K



1: Pin

2: Vapc

3: Vdd 4: Pout

G: GND

Absolute Maximum Ratings ($Tc = 25^{\circ}C$)

Item	Symbol	Rating	Unit	
Supply voltage	V _{DD}	10	V	
Supply current	I _{DD}	3	А	
V _{APC} voltage	V_{APC}	4	V	
Input power	Pin	10	mW	
Operating case temperature	Tc (op)	-30 to +100	°C	
Storage temperature	Tstg	-30 to +100	°C	
Output power	Pout	5	W	

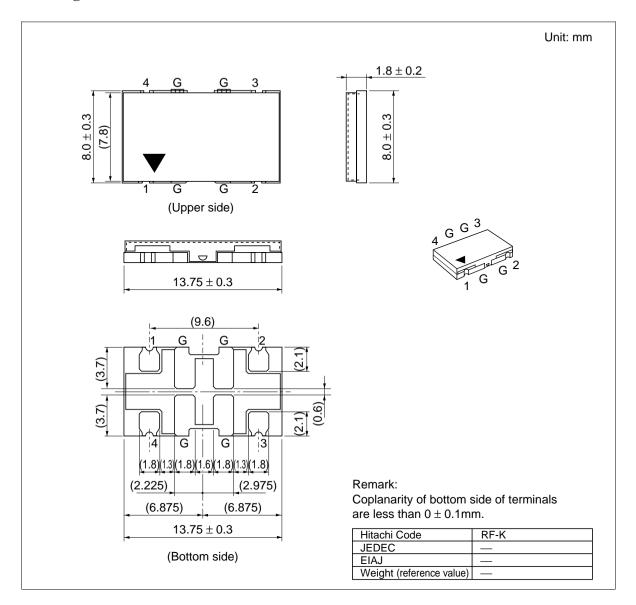


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Electrical Characteristics ($Tc = 25^{\circ}C$)

Item	Symbol	Min	Тур	Max	Unit	Test Condition
Frequency range	f	880	_	915	MHz	
Control voltage range	V _{APC}	0.5	_	3.0	V	
Drain cutoff current	I _{DS}	_	_	100	μΑ	$V_{DD} = 10 \text{ V}, V_{APC} = 0 \text{ V}$
Total efficiency	$\eta_{\scriptscriptstyle \sf T}$	40	45	_	%	$Pin = 1 \text{ mW}, V_{DD} = 4.8 \text{ V},$
2nd harmonic distortion	2nd H.D.	_	-45	-35	dBc	Pout = 3.8 W, Vapc = controlled
3rd harmonic distortion	3rd H.D.	_	-45	-35	dBc	$R_L = Rg = 50 \Omega$, $Tc = 25$ °C
Input VSWR	VSWR (in)	_	1.5	3	_	-
Output power (1)	Pout (1)	3.8	4.3	_	W	Pin = 1 mW, V_{DD} = 4.8 V, V_{APC} = 3.0 V, R_{L} = Rg = 50 Ω, Tc = 25°C
Output power (2)	Pout (2)	2.5	2.9	_	W	Pin = 1 mW, V_{DD} = 4.3 V, V_{APC} = 3.0 V, R_{L} = Rg = 50 Ω, Tc = 80°C
Isolation	_	_	- 50	-40	dBm	Pin = 1 mW, V_{DD} = 4.8 V, V_{APC} = 0.5 V, R_{L} = Rg = 50 Ω, Tc = 25°C
Switching time	tr, tf	_	1	2	μs	Pin = 1 mW, V_{DD} = 4.8 V, Pout = 3.8 W, R_{L} = Rg = 50 Ω, Tc = 25°C
Stability & Load VSWR tolerance	_	No parasitic oscillation & No degradation				Pin = 1 mW, V_{DD} = 4 to 7 V, Pout \leq 3.8 W, Vapc \leq 3 V GSM pulse. Rg = 50 Ω , t = 20sec., Tc = 25°C, Output VSWR = 6 : 1 All phases

Package Dimensions



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